



30V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

| BV _{DSS} | R _{DS(ON)} Max | I _D Max T _C = +25°C |
|-------------------|-------------------------------|--|
| | 3.8mΩ @ V _{GS} = 10V | 145A |
| 30V | 6mΩ @ V _{GS} = 4.5V | 115A |

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low R_{DS(ON)} Minimizes On-State Losses
- Excellent Q_{gd} x R_{DS(ON)} Product (FOM)
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% Unclamped Inductive Switching Ensures More Reliability
- Rated to +175°C Ideal for High Ambient Temperature Environments
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH3004LPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

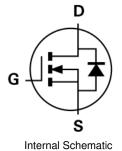
Mechanical Data

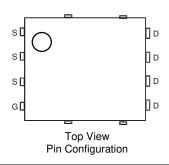
- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Weight: 0.097 grams (Approximate)



Top View







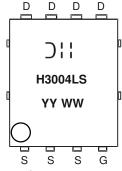
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|-----------------|---------------|-------------------|
| DMTH3004LPSQ-13 | PowerDI5060-8 | 2,500/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



⊃¦¦ = Manufacturer's Marking H3004LS = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 21 = 2021) WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|---|---|-------|------------|---|
| Drain-Source Voltage | V_{DSS} | 30 | V | |
| Gate-Source Voltage | | Vgss | +20 -16 | V |
| Continuous Drain Current (Note 5) | $T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$ | lo | 22 16 | А |
| Continuous Drain Current (Note 6) $ T_C = +25^{\circ}C $ $T_C = +100^{\circ}C $ | | lo | 145 103 | А |
| Maximum Continuous Body Diode Forward Current | Is | 100 | Α | |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | I _{DM} | 180 | Α | |
| Avalanche Current, L=0.3mH | I _{AS} | 27 | Α | |
| Avalanche Energy, L=0.3mH | Eas | 110 | mJ | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | |
|--|-------------------|-------------|------|--|
| Total Power Dissipation | PD | 136 | W | |
| Thermal Resistance, Junction to Ambient (Note 5) | Reja | 47 | °C/W | |
| Thermal Resistance, Junction to Case (Note 6) | R ₀ JC | 1.1 | G/VV | |
| Operating and Storage Temperature Range | TJ, TSTG | -55 to +175 | °C | |

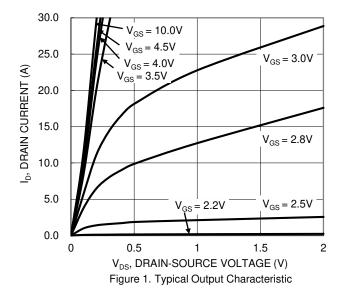
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

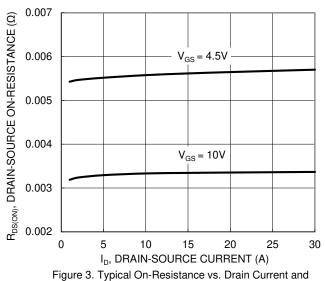
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition |
|--|-------------------|------|------|------|--------------------|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 30 | _ | _ | V | $V_{GS} = 0V, I_{D} = 250\mu A$ |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μΑ | $V_{DS} = 24V, V_{GS} = 0V$ |
| Zero Gate Voltage Drain Current (Note 8) | I _{DSS} | _ | _ | 10 | μΑ | V _{DS} = 24V, V _{GS} = 0V T _J = +125°C |
| Gate-Source Leakage | Igss | _ | _ | ±100 | nA | V _{GS} = +20V, V _{DS} = 0V V _{GS} = -16V, V _{DS} = 0V |
| ON CHARACTERISTICS (Note 7) | | | | | | |
| Gate Threshold Voltage | VGS(TH) | 1 | 1.6 | 3 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ |
| Static Drain-Source On-Resistance | RDS(ON) | _ | 3.3 | 3.8 | mΩ | $V_{GS} = 10V, I_D = 20A$ |
| Static Dialif-Source Off-Resistance | | _ | 5 | 6 | 11177 | $V_{GS} = 4.5V, I_{D} = 7A$ |
| Diode Forward Voltage | VsD | _ | 0.70 | 1 | V | $V_{GS} = 0V$, $I_{S} = 1A$ |
| DYNAMIC CHARACTERISTICS | | | | | | |
| Input Capacitance (Note 8) | Ciss | _ | 2370 | _ | | V _{DS} = 15V, V _{GS} = 0V, f = 1MHz |
| Output Capacitance (Note 8) | Coss | _ | 1360 | _ | pF | |
| Reverse Transfer Capacitance (Note 8) | Crss | _ | 240 | _ | | |
| Gate Resistance | Rg | 0.14 | 0.7 | 1.75 | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ |
| SWITCHING CHARACTERISTICS (Note 8) | | | | | | |
| Total Gate Charge (Vgs = 10V) | Qg | _ | 43.7 | _ | | |
| Gate-Source Charge | Q_{gs} | _ | 6.9 | _ | nC | $V_{DS} = 15V, I_{D} = 20A$ |
| Gate-Drain Charge | Q_{gd} | _ | 8 | _ | | |
| Turn-On Delay Time | td(ON) | _ | 6.2 | _ | | $V_{DD}=15V,V_{GS}=10V,\\ R_G=3\Omega,R_L=0.75\Omega$ |
| Turn-On Rise Time | tR | _ | 4.2 | _ | 20 | |
| Turn-Off Delay Time | tD(OFF) | _ | 21 | _ | ns | |
| Turn-Off Fall Time | tF | _ | 8 | _ | | |
| Body Diode Reverse Recovery Time | trr | _ | 25 | _ | ns I 154 W/W 500A/ | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 37 | _ | nC | I _F = 15A, dl/dt = 500A/μs |

Notes:

Device mounted with exposed drain pad on 25mm by 25mm 2oz copper on a single- sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady state.
 Thermal resistance from junction to soldering point (on the exposed drain pad).
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.







Gate Voltage

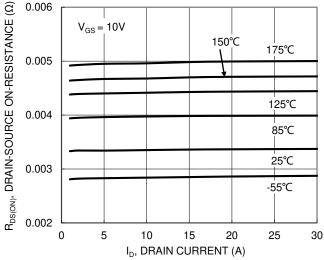
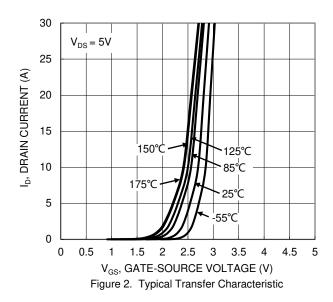
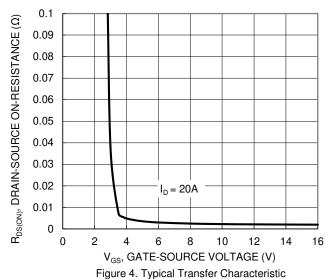


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





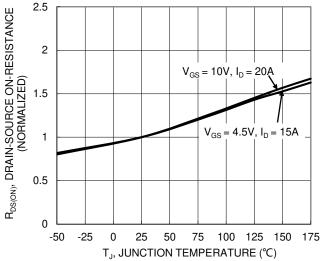


Figure 6. On-Resistance Variation with Junction Temperature



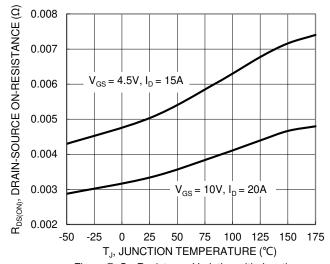


Figure 7. On-Resistance Variation with Junction Temperature

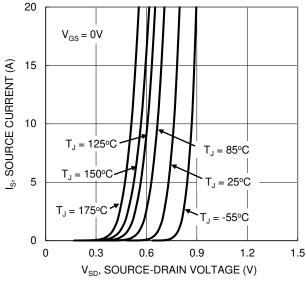


Figure 9. Diode Forward Voltage vs. Current

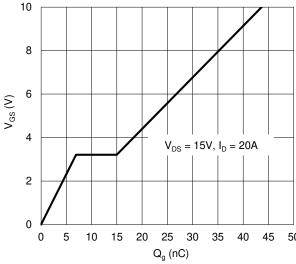


Figure 11. Gate Charge

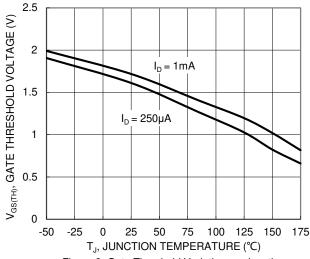


Figure 8. Gate Threshold Variation vs. Junction Temperature

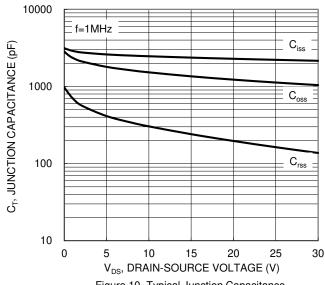
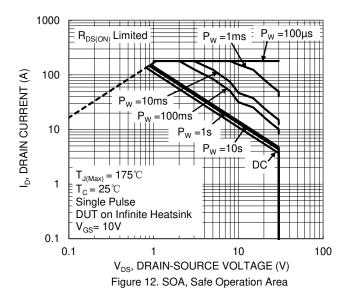


Figure 10. Typical Junction Capacitance





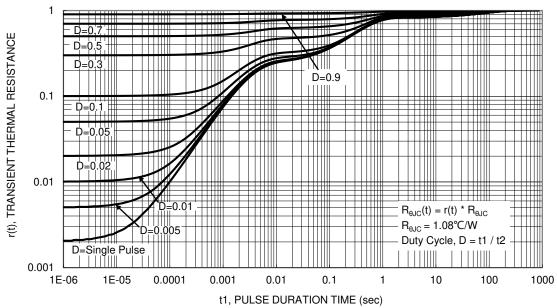


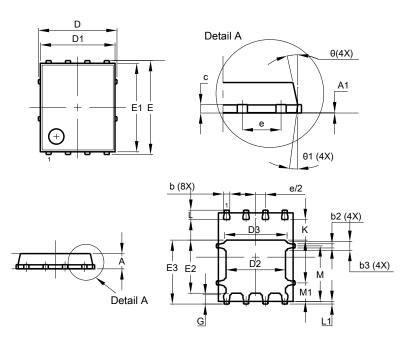
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

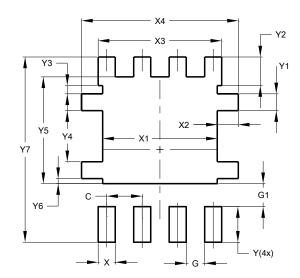


| PowerDI5060-8 | | | | | |
|----------------------|----------|----------|-------|--|--|
| Dim | Min | Тур | | | |
| Α | 0.90 | 1.10 | 1.00 | | |
| A1 | 0.00 | 0.05 | _ | | |
| b | 0.33 | 0.51 | 0.41 | | |
| b2 | 0.200 | 0.350 | 0.273 | | |
| b3 | 0.40 | 0.80 | 0.60 | | |
| С | 0.230 | 0.330 | 0.277 | | |
| D | ļ, | 5.15 BSC | ; | | |
| D1 | 4.70 | 5.10 | 4.90 | | |
| D2 | 3.70 | 4.10 | 3.90 | | |
| D3 | 3.90 | 4.30 | 4.10 | | |
| Е | (| 6.15 BSC | ; | | |
| E1 | 5.60 | 6.00 | 5.80 | | |
| E2 | 3.28 | 3.68 | 3.48 | | |
| E3 | 3.99 | 4.39 | 4.19 | | |
| е | 1.27 BSC | | | | |
| G | 0.51 | 0.71 | 0.61 | | |
| K | 0.51 | - | - | | |
| L | 0.51 | 0.71 | 0.61 | | |
| L1 | 0.100 | 0.200 | 0.175 | | |
| М | 3.235 | 4.035 | 3.635 | | |
| M1 | 1.00 | 1.40 | 1.21 | | |
| Θ | 10° | 12° | 11° | | |
| Θ1 | 6° | 8° | 7° | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| С | 1.270 | | | |
| G | 0.660 | | | |
| G1 | 0.820 | | | |
| X | 0.610 | | | |
| X1 | 4.100 | | | |
| X2 | 0.755 | | | |
| Х3 | 4.420 | | | |
| X4 | 5.610 | | | |
| Υ | 1.270 | | | |
| Y1 | 0.600 | | | |
| Y2 | 1.020 | | | |
| Y3 | 0.295 | | | |
| Y4 | 1.825 | | | |
| Y5 | 3.810 | | | |
| Y6 | 0.180 | | | |
| Y7 | 6.610 | | | |



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